



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Nguyen et al.

Patent No.: 7,128,806

Issued: October 31, 2006

Serial No.: 10/689,783

Filed: October 21, 2003

For: MASK ETCH PROCESSING
APPARATUS

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§ Group Art Unit: 1763
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§ Examiner: Rakesh K. Dhingra
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Certificate of Correction Branch
Commissioner for Patents
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CERTIFICATE OF MAILING 37 CFR 1.8	
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<u>1/26/07</u> Date	<u>Kim ~ zhs</u> Signature

Dear Sir:

REQUEST FOR CERTIFICATE OF CORRECTION

Attached is a Certificate of Correction for correcting several errors throughout the printed patent.

Applicants submit that the errors mentioned above were not made by the applicants, but were made during the printing of the patent.

Respectfully submitted,

Certificate
FEB 01 2007
of Correction

Kim ~ zhs
Keith M. Tackett
Registration No. 32,008
PATTERSON & SHERIDAN, L.L.P.
3040 Post Oak Blvd. Suite 1500
Houston, TX 77056
Telephone: (713) 623-4844
Facsimile: (713) 623-4846
Agent for Applicant(s)

FEB 5 2007

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,128,806

Page 1 of 1

APPLICATION NO. : 10/689,783

DATED : October 31, 2006

INVENTOR(S) : Nguyen et al.

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

Title Page, Item [57], ABSTRACT, Line 4: Change "comprising-a" to --comprising a--

Column 2, Line 67: Insert a semicolon after "ring"

Column 6, Line 62: Change "MxPTM" to --MxP™--

Column 7, Lines 41-51: The paragraph beginning on line 41 should read:

--The supporting apparatus and substrate handler blade 300 described above may also be taken advantage of in a substrate processing system 410 providing support for a substrate. The substrate processing system 410 may include a transfer chamber 414, at least one processing chamber 160 with a substrate support member 100 with a support surface and a capture ring coupled to the support surface, the capture ring adapted to receive a substrate, and a substrate handler 418 disposed in the transfer chamber 414. The substrate handler 418 preferably has a substrate handler blade 300 described above. The process chambers are preferably plasma etch chambers.--

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Keith M. Tackett
PATTERSON & SHERIDAN, L.L.P.
3040 Post Oak Blvd., Suite 1500
Houston, TX 77056-6582

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